

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TOSHIBA AMERICA ELECTRONIC COMPONENTS, INC.	09/15/2014
<b>RECEIVING PARTY DATA</b>	
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14489365
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<b>NAME OF SUBMITTER:</b>	FREDERICK D. KIM
<b>SIGNATURE:</b>	/Frederick D. Kim/
<b>DATE SIGNED:</b>	09/17/2014
<b>Total Attachments: 2</b>	
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## ASSIGNMENT

**WHEREAS**, the undersigned inventor(s) (hereinafter referred to as "INVENTOR(S)") desire(s) to transfer to Toshiba America Electronic Components, Inc. (hereinafter referred to as "TAEC"), organized and existing under the laws of the United States, having a place for the transaction of business at 9740 Irvine Boulevard, Suite D700, Irvine, CA 92618, all right, title and interest in and to the inventions disclosed in the following Invention Disclosure Form(s):

- "HYBRID-HDD POLICY FOR WHAT HOST-R/W DATA GOES INTO NAND" submitted by Eric R. Dunn and Richard M. Ehrlich, on [9/30/2013];

And such inventions which if now or hereafter are disclosed in the patent application(s):

- (a)  U.S. patent application executed on \_\_\_\_\_,
- (b)  U.S. application no. \_\_\_\_\_ filed on \_\_\_\_\_,
- (c)  International (e.g., PCT, JP) application no. \_\_\_\_\_ filed on \_\_\_\_\_,

(collectively, the "INVENTIONS");

**WHEREAS**, TAEC desires to acquire all of the right, title and interest of INVENTOR(S) in, to and under the INVENTIONS and TAEC further desires to transfer all such right, title and interest to Kabushiki Kaisha Toshiba (hereinafter referred to as "TOSHIBA") a corporation duly organized and existing under the laws of Japan, with offices at 1-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8001;

**NOW, THEREFORE**, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, INVENTOR(S) hereby sell(s), assign(s) and transfer(s) to TAEC the entire right, title and interest for the United States and its territorial possessions, and in all foreign countries, in and to the INVENTIONS and any and all improvements thereon which are the subject of the INVENTIONS, and in and to any U.S. or foreign patent application for such INVENTIONS and improvements and any legal equivalent thereof in a foreign country, including the right to claim priority, and in and to any division, continuation or continuation-in-part, renewal or substitute thereof, and in and to all resulting Letters Patents or any reissue, reexamination certificate, supplemental examination certificate, post grant review certificate, inter partes review certificate, or otherwise, thereof, to have and to hold the same to the full end of the term or terms for which any and all of said Letters Patent may be granted (collectively, the "ASSIGNED INVENTIONS");

And for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, TAEC hereby sells, assigns and transfers to TOSHIBA the entire right, title and interest to the ASSIGNED INVENTIONS;

INVENTOR(S) and TAEC authorize and request the issuing authority to issue any and all patents on said application or applications to TOSHIBA or its successors and assigns;

INVENTOR(S) and TAEC hereby covenant that INVENTOR(S) and TAEC, respectively, has/have the full power to make this assignment, and that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment; and

Without further payment or compensation by TAEC, TOSHIBA or their successors and assigns, INVENTOR(S) further covenant(s) and agree(s) to communicate to TAEC, TOSHIBA, their representatives, agents, their successors or their assigns, or to subsequent assignees of the ASSIGNED INVENTIONS, any facts relating to the ASSIGNED INVENTIONS including evidence for purposes of interference or derivation proceedings or other administrative or legal proceedings whenever requested;

